SMTA 华南高科技会议 2016

2016 年 8 月 30 日－9 月 1 日

中国深圳展览中心

SMTA 中国将于 2016 年 8 月 30 日－9 月 1 日在深圳举办 SMTA 华南高科技会议 2016. 此次会议与第二十二届华南国际电子生产设备暨微电子工业展览会同期举办。此次会议将涉及行业中最热门的话题，包括电子组装/制造，工业/技术路标，商业焦点，新兴技术，实践技能发展，和无铅及其可靠性。

SMTA 华南高科技会议 2016 节目			
	8 月 30 日 (星期二)	8 月 31 日 (星期三)	9 月 1 日 (星期四)
高科技技术研讨会	10:30-15:00	10:30-15:30	
高科技设备技术研讨会	10:30-15:30	10:30-15:30	10:30-12:30
中国 SMTA 十周年庆典	15:30-16:30		
展览会	第二十二届华南国际电子生产设备暨微电子工业展		

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<u>高科技技术研讨会/高科技设备技术研讨会主题(**2016 年 8 月 30 日－9 月 1 日**)</u>

主题覆盖面包括：

先进封装及元件	增材制造	非焊接式互联
2.5/3D 封装和集成	SMT 粘胶	供应工程
BGA/CSP	替代焊料合金	热压打线
生物技术封装	BGA/CSP 装配	底部填充、边角固定及聚合物强化
元件存储	底部端子元件	汽相焊接
连接器技术	空腔基板装配	良率改善
铜柱	清洗、敷型涂覆及注胶	
铜线打线	基板联接装配	**商业与供应链**
扩散打线	DFX 和零缺陷设计	产能模型
嵌入及微型被动元件	基板上芯片直装	冲突矿产
环境测试	点胶与底部填充胶	合同制造
故障分析技术	环氧树脂助焊剂	高仿器件
倒装芯片	工厂设施布置	海外业务
耐高温封装	无卤与零卤素	环境问题
引脚处理	头枕缺陷、翘曲相关锡点缺陷	精益制造
磁力焊接	高熔点焊料	在岸外包
微型机电系统及传感器	激光焊接	营运管理
湿度敏感器件	无引脚阵平面列封装	器件废除
封装堆叠(PoP)	无铅焊接及可靠性	RoHS/REACH 合规
光子学	低温焊接	供应商管理
光伏太阳能	小批量与原型机	技术路线图
可靠性	无润湿空焊	
银线打线	封装堆叠装配	**新兴技术**
裸芯片堆叠	器件废除	<=0.3mm 间距平面阵列技术
系统级封装	贴装	3D 电路
穿透硅通孔	印刷	3D 打印和设计规范
锡须	回流焊接与波峰焊接	先进封装
晶圆级封装	精密复杂器件返修可靠性	柔性板装配
	机器人焊接	玻璃板装配
装配	选择性焊接	空腔板装配
01005/03015 元件及装配	喷涂式点锡膏	消费电子
3D 装配	焊锡膏与焊点空洞	嵌入式主动技术

SMTA 华南高科技会议 2016

2016 年 **8** 月 **30** 日—**9** 月 1 日

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嵌入式被动技术 柔性电子 焊锡膏喷涂 LED 技术、装配和可靠性 微机电系统、微光机电系统及射频技术 微系统封装、微系统模组 纳米材料 纳米技术、材料和电子 新材料与制程 光电技术 塑料 3D 基板联接 功耗和散热管理 电源电子 印刷电子技术 纳米器件的可靠性 助焊剂增强型锡膏 传感器与制造 智能制造系统 小型芯片切单 固体照明 太阳能技术 系统级封装 热介质材料 触摸屏技术 虚拟原型机 可穿戴电子 无线电器	**环保应用(军工、航天、汽车、工业、石油天然气)** 替代能源 电池剩余电量估算 元件与可靠性 铜腐蚀 COTS 高铅焊料替代 耐高温电子 无铅问题 非破坏性检查 微断层造影技术 多物理场耦合分析模型 基材与表面处理 散热管理 锡须 **基板技术** 生物相容基材 黑焊盘和表面处理缺陷 导电阳极丝 (CAF) 爬行腐蚀 嵌入式被动、主动元件 无卤 高密度集成 HDI 高功率基板 微通孔(包括填充与非填充) 湿度敏感器件 新型层压板材料 新型表面处理和可靠性 焊盘坑裂 阻焊膜 基材可靠性	**制程控制** 声学成像(C-SAM) 自动光学检查的效益 计算机集成制造(CIM) ICT 在线测试 工艺制程模型 软件 测试策略 2D/3D X 光检查

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SMTA 中国十周年庆典（2016 年 8 月 30 日）

这是一个很好的机会在中国 SMTA 十周年庆典上与我们业界的朋友们见面. 另外，为了感谢演讲者们在高科技研讨会和高科技设备技术研讨会中优秀信息的分享，中国 SMTA 十周年庆典上颁发最佳论文奖和最佳演讲奖.

查询及报名：电邮至 peggychen@smta.org.cn

SMTA China South Conference 2016

30 August – 1 September 2016
Shenzhen Convention & Exhibition Center, China

The SMTA China will organize the SMTA China South Conference 2016 in Shenzhen on 30 August-1September, 2016. This timely event will be held in conjunction with NEPCON South China 2016. This events will address the industry's most pressing issues in electronics assembly/ manufacturing, industry/ technology roadmap, business focus, advanced packaging, practical skill development, emerging technologies, and lead-free & reliability.

SMTA China South Conference 2016 Program			
	30 August (Tuesday)	31 August (Wednesday)	1 September (Thursday)
Technology Conference	10:30-15:00	10:30-15:30	
Vendor Conference	10:30-15:30	10:30-15:30	10:30-12:30
SMTA China 10th Anniversary Ceremony	15:30-16:30		
Trade Show	NEPCON South China 2016		

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Technology Conference/Vendor Conference Topics (30 August-1 Septermber 2016)

Topical coverage includes:

Advanced Packaging/Components
- 2.5/3D Packaging and Integration
- BGA/CSP
- Biomedical Packaging
- Component Storage
- Connector Technology
- Copper Pillars
- Copper Wire Bonding
- Diffusion Bonding
- Embedded and Miniature Passives
- Environmental Testing
- Failure Analysis Techniques
- Flip Chip
- High Temperature Packaging
- Lead Finishes
- Magnetic Soldering
- MEMS and Sensors
- Moisture Sensitive Devices (MSD)
- Package on Package (PoP)
- Photonics
- Photovoltaics and Solar
- Reliability
- Silver Wire-bonding
- Stacked Die
- System in Package (SiP)
- Through Silicon Vias (TSVs)
- Tin Whiskers
- Wafer Level Packaging (WLP)

Assembly
- 01005/03015 Components/Assembly
- 3D Board Assembly
- Additive Manufacturing
- SMT Adhesives
- Alternate Solder Alloys
- BGA/CSP Assembly
- Bottom Terminated Components
- Cavity Board Assembly
- Cleaning, Conformal Coating and Potting
- Connector Assembly to PCB
- DFX/Design for Six Sigma
- Direct Chip Attach to PCB (DCA)
- Dispensing & Underfill
- Epoxy Fluxes
- Facility Layout
- Halogen and Halogen-Free
- Head on Pillow Defect/Warpage Induced Solder Joint Defects
- High Melting Point Solder
- Laser Soldering
- Leadless Area Array Packages
- Lead-Free Soldering/Reliability
- Low Temperature Processing
- Low Volume/Prototype
- Non-Wet Open (NWO) Defects
- Package-on-Package Assembly
- Part Obsolescence
- Placement
- Printing
- Reflow Soldering/ Wave Soldering
- Rework and Repair of QFNs (01005, Leadless Components, PoP, Rework Reliability
- Robotic Soldering
- Selective Soldering
- Solder Jetting
- Solder Paste/Solder Voids in Joints
- Solderless Interconnections
- Supplier Engineering
- Thermo Compression Bonding
- Underfill/ Corner Glue/ Other Polymeric Reinforcements
- Vapor Phase Reflow
- Yield Improvement

Business/Supply Chain
- Capacity Modeling
- Conflict Minerals
- Contract Manufacturing
- Counterfeit Parts
- Doing Business in Overseas
- Environmental Issues
- Lean Manufacturing
- Onshoring
- Operations Management
- Part Obsolescence
- RoHS/REACH Compliance
- Supplier Management
- Technology Roadmaps

Emerging Technologies
- <= 0.3mm Pitch Area Array Technologies
- 3D Circuits
- 3D Printing & Design Rules
- Advanced Packaging
- Assembly to Flex Substrates
- Assembly to Glass Substrates
- Cavity Assembly
- Consumer Applications
- Embedded Active Technology
- Embedded Passive Technology
- Flexible Electronics
- Jetting of Solder Pastes
- LED Technology/Assembly/Reliability
- MEMS/RF/MOEMS
- Microsystems Packaging / Modular Microsystems
- Nanomaterials
- Nanotechnology, Materials, & Electronics
- New Materials and Processes
- Optoelectronics
- Plastic 3D PCB to PCB Technology
- Power or Thermal Management
- Power Electronics
- Printed Electronics Technology
- Reliability of Nanodevices
- Resin Reinforcement Solder Pastes
- Sensors and Manufacturing
- Smart Manufacturing Systems
- Small Die Size Singulation
- Solid State Lighting
- Solar Technology
- System in a Package
- Thermal Interface Materials
- Touch Screen Technologies
- Virtual Prototyping
- Wearable Electronics
- Wireless Applications

Harsh Environment Applications (Military, Aerospace, Automotive, Industrial, Oil & Gas)
- Alternate Energy
- Battery Prognostics
- Components and Reliability
- Copper Corrosion
- COTS
- High Lead Solder Replacement
- High Temperature Electronics
- Lead-free Issues
- Non-Destructive Inspection
- Micro-Computed Tomography
- Multiphysics Modeling
- Substrates and Finishes
- Thermal Management
- Tin Whiskers

SMTA China South Conference 2016

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PCB Technology
- Bio-Compatible Substrates
- Black Pad and Surface Finish Defects
- Conductive Anodic Filament (CAF)
- Creep Corrosion
- Embedded Passive/Active Components
- Halogen Free
- HDI
- High Power PCBs
- Micro-vias (including filled/unfilled)
- Moisture Sensitivity
- New Laminate Materials
- New Surface Finishes & Solderability
- Pad Cratering
- Soldermask
- Substrate Reliability

Process Control
- Acoustic Imaging(C-SAM)
- Benefits of AOI&SPI
- CIM
- In-Circuit Test
- Process Modelling
- Software
- Test strategles
- 2D/3D X-Ray

SMTA China 10th Anniversary Ceremony

(30 August 2016)

It is a great opportunity to meet with our friends in the SMT Industry at the SMTA China Anniversary Ceremony. In addition, in order to appreciate the speakers of excellent information sharing, SMTA China would like to honor the best paper, and the speaker of best presentation, which award will be presented during the Ten Anniversary Ceremony of SMTA China.

Enquiry and Registration: E-mail to peggychen@smta.org.cn